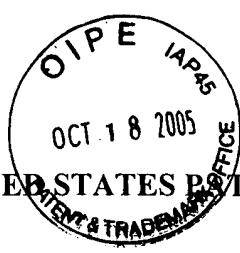


Docket No.: 060188-0717



PATENT JRW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 20277
OKAMURA, HIDEAKI, et al. : Confirmation Number: 4226
Application No.: 10/720,197 : Group Art Unit: 2811
Filed: November 25, 2003 : Examiner: Not yet assigned
For: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

REQUEST FOR CORRECTED FILING RECEIPT

Mail Stop OFR
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Attached is a copy of the Filing Receipt received from the U.S. Patent and Trademark Office in the above-referenced application. It is noted that the Foreign Application date contains an error. Attached is a copy of the Declaration and Power of Attorney, which evidences that the Foreign Application data should be recorded as:

JAPAN 2002-352778 12/04/2002 (December 4, 2002)

It is requested that a corrected filing receipt be issued.

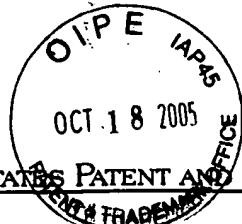
Respectfully submitted,

McDERMOTT WILL & EMERY LLP

Michael E. Fogarty
Registration No. 36,139

Please recognize our Customer No. 20277
as our correspondence address.

600 13th Street, N.W.
Washington, DC 20005-3096
Phone: 202.756.8000 MEF:gav
Facsimile: 202.756.8087
Date: October 18, 2005



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
 United States Patent and Trademark Office
 Address: COMMISSIONER FOR PATENTS
 P.O. Box 1450
 Alexandria, Virginia 22313-1450
www.uspto.gov

APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE RECD	ATTY.DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/720,197	11/25/2003	2811	770	60188-717	3	7	1

Jack Q. Lever, Jr.
 McDERMOTT, WILL & EMERY
 600 Thirteenth Street, N.W.
 Washington, DC 20005-3096

R E C E I V E D
 JUN 14 2004

MW&E

CONFIRMATION NO. 4226

REPLACEMENT FILING RECEIPT



OC000000012876240

Date Mailed: 06/04/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Hideaki Okamura, Osaka, JAPAN;
 Takao Yamaguchi, Kyoto, JAPAN;
 Tomoyuki Sasaki, Kyoto, JAPAN;

Assignment For Published Patent Application

MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.;

Domestic Priority data as claimed by applicant

Foreign Applications

JAPAN 2002-352778 04/12/2002

If Required, Foreign Filing License Granted: 02/24/2004

Projected Publication Date: Not Applicable

Non-Publication Request: No

Early Publication Request: No

Title

Method for fabricating semiconductor device

Preliminary Class

257

**LICENSE FOR FOREIGN FILING UNDER
Title 35, United States Code, Section 184
Title 37, Code of Federal Regulations, 5.11 & 5.15**

GRANTED

The applicant has been granted a license under 35 U.S.C. 184, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" followed by a date appears on this form. Such licenses are issued in all applications where the conditions for issuance of a license have been met, regardless of whether or not a license may be required as set forth in 37 CFR 5.15. The scope and limitations of this license are set forth in 37 CFR 5.15(a) unless an earlier license has been issued under 37 CFR 5.15(b). The license is subject to revocation upon written notification. The date indicated is the effective date of the license, unless an earlier license of similar scope has been granted under 37 CFR 5.13 or 5.14.

This license is to be retained by the licensee and may be used at any time on or after the effective date thereof unless it is revoked. This license is automatically transferred to any related applications(s) filed under 37 CFR 1.53(d). This license is not retroactive.

The grant of a license does not in any way lessen the responsibility of a licensee for the security of the subject matter as imposed by any Government contract or the provisions of existing laws relating to espionage and the national security or the export of technical data. Licensees should apprise themselves of current regulations especially with respect to certain countries, of other agencies, particularly the Office of Defense Trade Controls, Department of State (with respect to Arms, Munitions and Implements of War (22 CFR 121-128)); the Office of Export Administration, Department of Commerce (15 CFR 370.10 (j)); the Office of Foreign Assets Control, Department of Treasury (31 CFR Parts 500+) and the Department of Energy.

NOT GRANTED

No license under 35 U.S.C. 184 has been granted at this time, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" DOES NOT appear on this form. Applicant may still petition for a license under 37 CFR 5.12, if a license is desired before the expiration of 6 months from the filing date of the application. If 6 months has lapsed from the filing date of this application and the licensee has not received any indication of a secrecy order under 35 U.S.C. 181, the licensee may foreign file the application pursuant to 37 CFR 5.15(b).



MUS-4 - 207401

Docket No. _____

COMBINED DECLARATION/POWER OF ATTORNEY
FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled
METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

(check one) is attached hereto.

was filed on _____ as
Application Serial No. _____.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)	Priority Claimed		
2002-352778 (Number)	JAPAN (Country)	04/12/2002 (Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Appln. Serial No.)	(Filing Date)	(Status-patented, pending, abandoned)
---------------------	---------------	---------------------------------------

(Appln. Serial No.)	(Filing Date)	(Status-patented, pending, abandoned)
---------------------	---------------	---------------------------------------

I hereby appoint as my attorneys, with full power of substitution and revocation, to prosecute the patent application identified above and to transact all business in the U.S. Patent and Trademark Office connected therewith: Raphael V. Lupo (Reg. No. 28,363); Jack Q. Lever, Jr. (Reg. No. 28,149); Kenneth L. Cage (Reg. No. 26,151); Stanislaus Aksman (Reg. No. 28,562); Paul Devinsky (Reg. No. 28,553); Edward E. Kubasiewicz (Reg. No. 30,020), Michael E. Fogarty (Reg. No. 36,139); Brian E. Ferguson (Reg. No. 36,801); Robert W. Zelnick (Reg. No. 36,976); and Wilhlem F. Gadiano (Reg. No. 37,136).

Please address all correspondence and telephone calls to:

Jack Q. Lever, Jr.
 McDERMOTT, WILL & EMERY
 600 Thirteenth Street, N.W.
 Washington, D.C. 20005-3096
 (202) 756-8000

The undersigned hereby authorizes the U.S. attorneys named herein to accept and follow instructions from Maeda Patent Office as to any action to be taken in the Patent and Trademark Office regarding this application without direct communication between the U.S. attorney and the undersigned. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by the undersigned.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor Hideaki OKAMURA

Inventor's signature Hideaki OKAMURA Date November 19, 2003
 Residence* Osaka, Japan Citizenship Japan
 Post Office Address 2-21-6-205, Kosobe-cho, Takatsuki-shi, Osaka 569-1115, Japan

Full name of second inventor Takao YAMAGUCHI

Inventor's signature Takao Yamaguchi Date November 19, 2003
 Residence* Kyoto, Japan Citizenship Japan
 Post Office Address 490-503, Kuya-cho, Nishikikojidori-aburanokoji-higashiiru, Nakagyo-ku, Kyoto-shi, Kyoto 604-8232, Japan

Full name of third inventor Tomoyuki SASAKI

Inventor's signature Tomoyuki Sasaki Date November 19, 2003

Residence* Kyoto, Japan Citizenship Japan

Post Office Address 3-19-12, Seikadai, Seika-cho, Soraku-gun, Kyoto 619-0238, Japan

* City and State, or City and Country for foreign inventors